



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Delgado et al.

Attorney Docket No.: KLA1P083/P1039

Application No.: 10/688,839

Examiner: Unassigned

Filed: October 16, 2003

Group: 2877

Title: METHOD AND APPARATUS FOR
PROTECTING SURFACES OF OPTICAL
COMPONENTS

Confirmation No.: 9429

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on September 20, 2005 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed: _____

Linda L. Pollock
Linda L. Pollock

**INFORMATION DISCLOSURE STATEMENT
37 CFR §§1.56 AND 1.97(b)**

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449, non-U.S. copies which are attached, may be material to examination of the above-identified patent application. Applicants identify these references in compliance with their duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. The Examiner is requested to make these references of official record in this application.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that these references indeed constitute prior art.

This Information Disclosure Statement is: (i) filed within three (3) months of the filing date of the above-referenced application, (ii) believed to be filed before the mailing date of a first Office Action on the merits, or (iii) believed to be filed before the mailing of a first Office

Action after the filing of a Request for Continued Examination under §1.114. Accordingly, it is believed that no fees are due in connection with the filing of this Information Disclosure Statement. However, if it is determined that any fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 500388 (Order No. KLA1P083).

Respectfully submitted,

BEYER WEAVER & THOMAS, LLP

A handwritten signature in black ink, appearing to read "Hoellwarth", with a stylized flourish at the beginning.

Quin C. Hoellwarth

Registration No. 45,738

P.O. Box 70250
Oakland, CA 94612-0250



Form 1449 (Modified)	Atty. Docket No. KLA1P083/P1039	Application No.: 10/688,839
Information Disclosure Statement By Applicant	Applicant: Delgado et al.	
(Use Several Sheets if Necessary)	Filing Date October 16, 2003	Group 2877

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A	4,247,203	01-27-81	Levy et al.			04-03-78
	B	4,556,317	12-03-85	Sandland et al.			02-22-84
	C	4,618,938	10-21-86	Sandland et al.			02-22-84
	D	4,845,558	07-04-89	Tsai et al.			12-03-87
	E	5,031,976	07-16-91	Shafer			09-24-90
	F	5,488,229	01-30-96	Elliott et al.			10-04-94
	G	5,529,819	06-25-96	Campi, Jr.			04-17-95
	H	5,616,927	04-01-97	Kubota et al.			09-22-94
	I	5,691,088	11-25-97	Kubota et al.			09-22-92
	J	5,717,198	02-10-98	Broude et al.			07-10-95
	K	5,729,325	03-17-98	Kashida			01-29-97
	L	5,741,576	04-21-98	Kuo			09-06-95
	M	5,814,381	09-29-98	Kuo			04-04-97
	N	6,303,196	10-16-01	Funatsu			10-12-99
	O	6,313,467	11-06-01	Shafer et al.			06-16-00
	P	6,368,683	04-09-02	Shirasaki			03-27-00

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	J							

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	O	Wakamiya, "Status of 157nm Microstepper with High NA Lens," International Sematech, 157nm Technical Data Review dated May 7-9, 2002.
	P	Stokowski et al., "Wafer Inspection Technology Challenges for ULSI Manufacturing," KLA-Tencor.
	Q	"High-throughput scanning for patterned wafer inspection," http://www.kla-tencor.com/products/defect_control/aitxp/aitxp.html , downloaded June 11, 2002.
	R	"Automated e-beam inspection," http://www.kla-tencor.com/products/defect_control/es20xp/es20xp.html , downloaded June 11, 2002.

	S	"High-resolution imaging for patterned wafer inspection," http://www.kla-tencor.com/products/defect_control/2351/2351.html , downloaded June 11, 2002.
	T	"2351," February 2001, KLA-Tencor Corporation
	U	"KLA-Tencor offers 'mix-and-match' of e-beam, UV for wafer inspection," http://www.siliconstrategies.com/story/OEG20000710S0072 , downloaded June 11, 2002.
	V	"KLA-Tencor says Samsung cut DRAM development with UV inspection tool," http://www.siliconstrategies.com/story/OEG20010328S0021 , downloaded June 11, 2002.
	W	Press Release, "KLA-Tencor and Samsung Complete Joint Wafer Inspection Evaluation For Advanced DRAM Technology Production," http://www.kla-tencor.com/news_events/pr...leases/press_releases2001/9857400002.html , downloaded June 11, 2002.
	X	Stokowski et al., "Wafer Inspection Technology Challenges for ULSI Manufacturing – Part II, Yield Management Solutions, August 1999.
Examiner		Date Considered

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.